

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

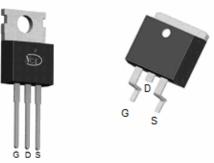
- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

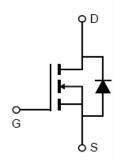
General Features

- V_{DS} =85V, I_D =95A $R_{DS(ON)}$ =5.4m Ω , typical (TO-220)@ V_{GS} =10V $R_{DS(ON)}$ =5.2m Ω , typical (TO-263)@ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!







Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP058N85	NCEP058N85	TO-220	-	-	-
NCEP058N85D	NCEP058N85D	TO-263	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	85	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	95	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	70	А
Pulsed Drain Current	I _{DM}	380	Α
Maximum Power Dissipation	P _D	125	W
Derating factor		0.83	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	599	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$ C



NCEP058N85, NCEP058N85D

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	1.2	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	60	°C/W

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition		Min	Тур	Max	Unit
Off Characteristics				•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA		85		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V		-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _E	os=0V	-	-	±100	nA
On Characteristics (Note 3)				- 1	l .		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=2$.50μA	2.0	3.0	4.0	V
Danie Course Ou Otata Basistana	Б	V _{GS} =10V, I _D =45A	TO-220	-	5.4	5.8	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}		TO-263		5.2	5.8	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =	45A		60	-	S
Dynamic Characteristics (Note4)				- 1	l .		l
Input Capacitance	C _{lss}	V _{DS} =40V,V _{GS} =0V, F=1.0MHz		-	3550	-	PF
Output Capacitance	Coss			-	540	-	PF
Reverse Transfer Capacitance	C _{rss}			-	22	-	PF
Switching Characteristics (Note 4)				- 1	l .		l
Turn-on Delay Time	t _{d(on)}	V_{DD} =40V, I_{D} =45A V_{GS} =10V, R_{G} =1.6 Ω		-	14.5	-	nS
Turn-on Rise Time	t _r			-	12	-	nS
Turn-Off Delay Time	$t_{d(off)}$			-	35	-	nS
Turn-Off Fall Time	t _f			-	13	-	nS
Total Gate Charge	Qg)/ 40\/I	454	-	67	-	nC
Gate-Source Charge	Q_{gs}	V _{DS} =40V,I _D =45A, V _{GS} =10V		-	20		nC
Gate-Drain Charge	Q_{gd}			-	20		nC
Drain-Source Diode Characteristics	1			1		l l	
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =45A		-		1.2	V
Diode Forward Current (Note 2)	Is			-	-	95	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F	: = I _S	-	66	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)		-	140	-	nC

Notes:

^{1.} Repetitive Rating: Pulse width limited by maximum junction temperature.

^{2.} The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on R $P_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.

^{3.} Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

^{4.} Guaranteed by design, not subject to production

^{5.} EAS condition : Tj=25 $^{\circ}\!\!\mathrm{C}$,V_DD=40V,V_G=10V,L=0.5mH,Rg=25 $\!\Omega$



Typical Electrical and Thermal Characteristics

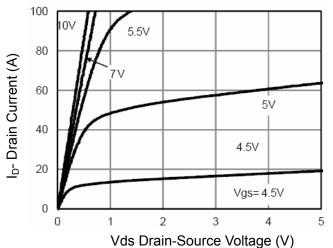
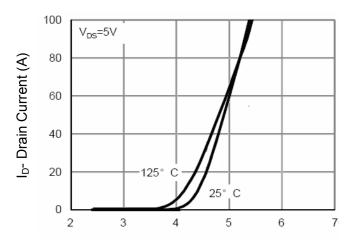


Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

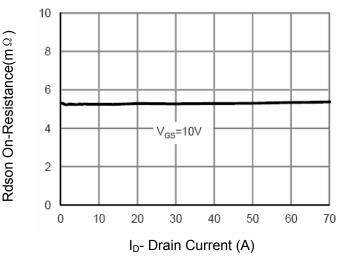


Figure 3 Rdson- Drain Current

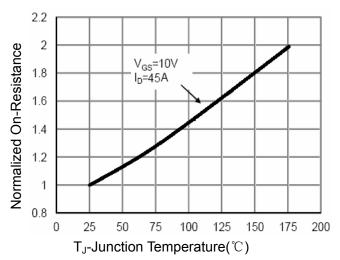


Figure 4 Rdson-Junction Temperature

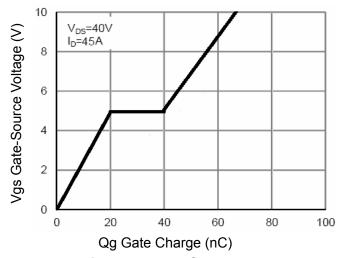


Figure 5 Gate Charge

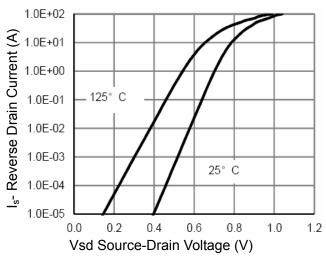


Figure 6 Source- Drain Diode Forward



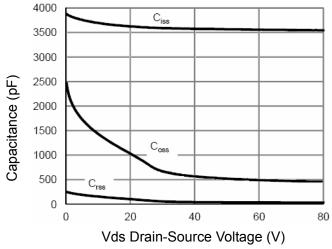


Figure 7 Capacitance vs Vds

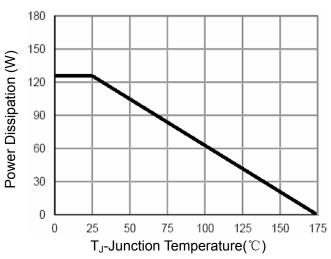


Figure 9 Power De-rating

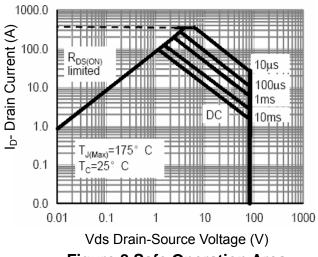


Figure 8 Safe Operation Area

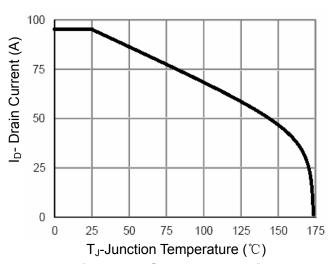


Figure 10 Current De-rating

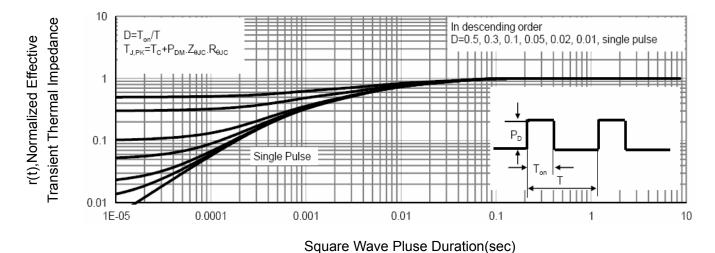
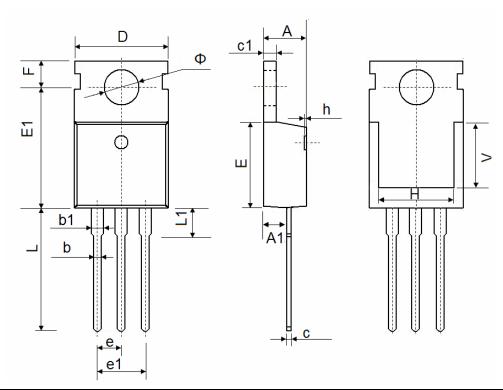


Figure 11 Normalized Maximum Transient Thermal Impedance



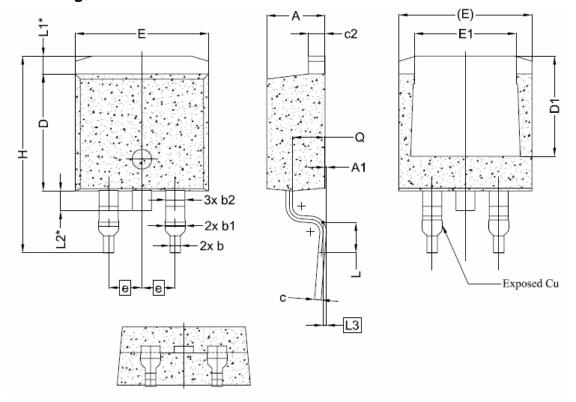
TO-220-3L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
Е	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.54	0 TYP.	0.100	TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	

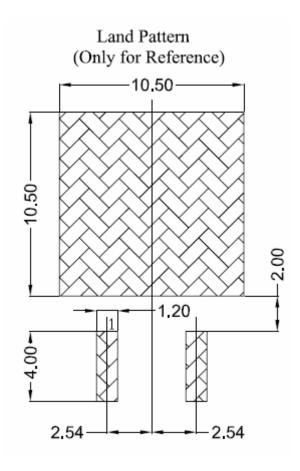


TO-263-2L Package Information



SYMBOL	DIMENSIONS				
SYMBOL	MIN.	NOM.	MAX.		
Α	4.24	4.44	4.64		
A1	0.00	0.10	0.25		
b	0.70	0.80	0.90		
b1	1.20	1.55	1.75		
b2	1,20	1,45	1,70		
С	0.40	0.50	0.60		
c2	1,15	1,27	1,40		
D	8.82	8.92	9.02		
D1	6.86 7.65		_		
E	9.96 10.16		10.36		
E1	6.89 7.77		7.89		
е	2,54 BSC				
Н	14,61	15,00	15,88		
L	1.78 2.32		2.79		
L1	1.36 REF.				
L2	1.50 REF.				
L3	0.25 BSC				
Q	2.30	2.70			





NCEP058N85, NCEP058N85D



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